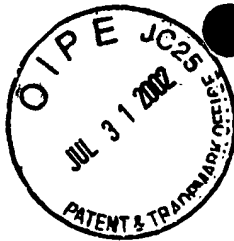


TS99-149B



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Application No. 09/755,282

July 23, 2002

TO: Commissioner of Patents and Trademarks  
Washington, D.C. 20231

FROM: George O. Saile, Reg. No. 19,572  
20 McIntosh Drive  
Poughkeepsie, N.Y. 12603

SUBJECT: Serial #: 09/755,282  
File Date: 01/08/01  
Inventor: CHEN, SHENG-HSIUNG  
Examiner: MITCHELL, JAMES  
Art Unit: 2827  
Title: METHOD OF IMPROVING COPPER PAD ADHESION

TECHNOLOGY CENTER 2800  
JUL 31 2002  
RECEIVED  
J. Mitchell  
8/13/02

#### RESPONSE TO OFFICE ACTION

This is in response to the office action dated May 23, 2002.

Please amend the above identified Divisional Application for  
patent as follows:

#### CERTIFICATE OF MAILING

I hereby certify that this correspondence is being deposited  
with the United States Postal Service as first class mail in an  
envelope addressed to: Commissioner of Patents and Trademarks,  
Washington, D.C. 20231 on July 23, 2002.

Signature

Date:

7/23/02

Stephen B. Ackerman, Reg. No. 37,761